



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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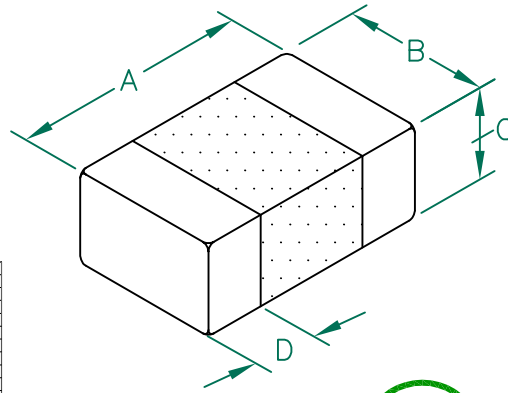


LI0805G201R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

A	2.00 [.079]	+ 0.20 [.008]
B	1.25 [.049]	+ 0.20 [.008]
C	0.90 [.035]	+ 0.20 [.008]
D	0.51 [.020]	+ 0.25 [.010]

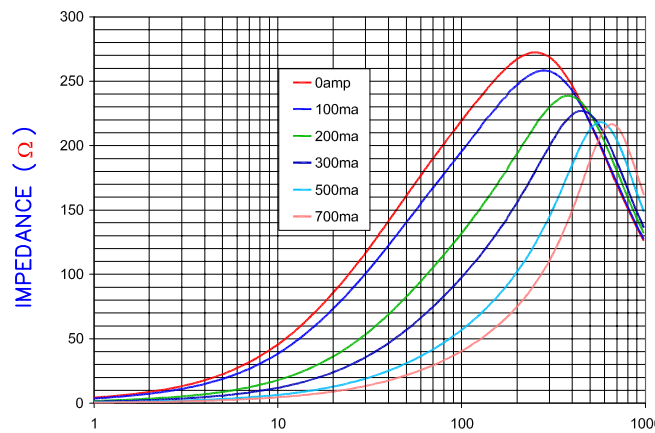


ELECTRICAL CHARACTERISTICS:

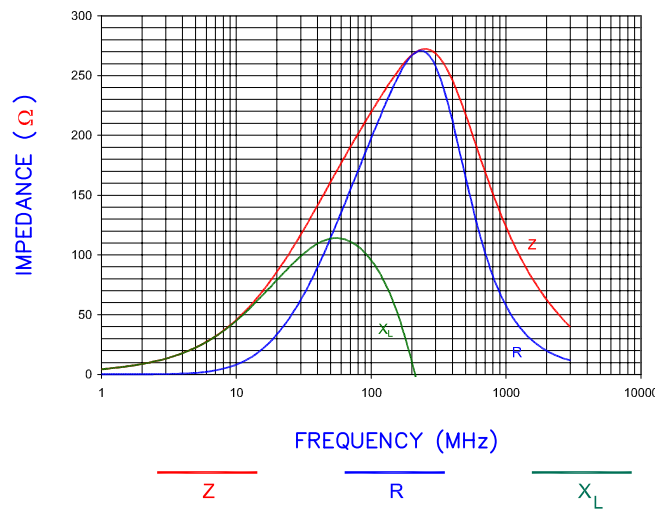
ELECTRICAL CHARACTERISTICS:		
Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	200	
Minimum	150	
Maximum	250	0.3
		700 mA

- NOTES: UNLESS OTHERWISE SPECIFIED
1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
 2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
 3. TERMINATION FINISH IS 100% TIN.
 4. OPERATING TEMP. RANGE: -40°C~+125°C. (INCLUDING SELF-HEATING)

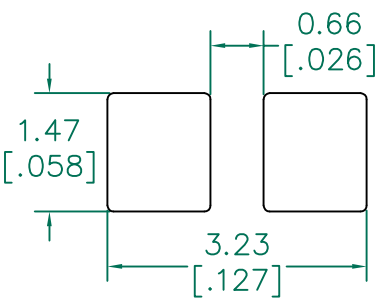
Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS



FREQUENCY (MHz)
|Z|, R, AND X vs. FREQUENCY

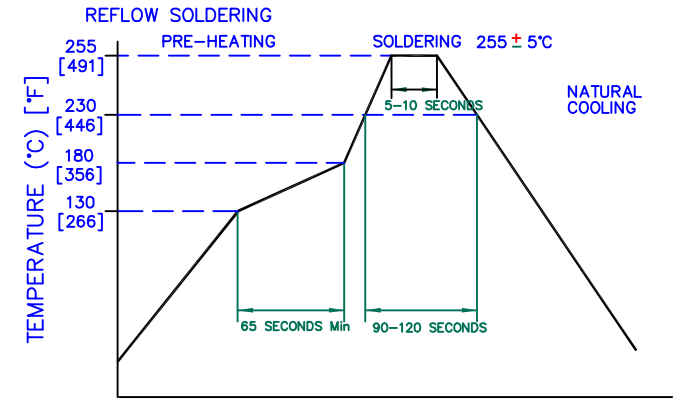


LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [.030] to this dimension.)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].

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F	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13			QU
E	CHANGE TO PAPER TAPE	03/03/10	JUN	PROJECT/PART NUMBER: LI0805G201R-10	
D	UPDATE COMPANY LOGO	06/16/09	JRK	REV: F	PART TYPE: CO-FIRE
C	ADD ROHS SYMBOL MODIFY NOTE 1	11/28/06	JRK	DATE: 04/19/04	SCALE: NTS
B	CORRECT TEST REF #	01/03/06	JRK	GAD #	TOOL #
A	ORIGINAL DRAFT	04/19/04	JRK	DESCRIPTION	INT
REV	DESCRIPTION	DATE	INT	LI0805G201R-10-F	2 of 2

